



Fabrication Notes

1. Fabricate PCB in accordance with IPC-6012, Class 2; per IPC-6011.
2. Layer Stackup
 1. Top Silkscreen
 2. Top Soldermask
 3. Top Copper, plate to 1oz/ft^2
 4. FR-4 or equivalent
 5. Bottom Copper, plate to 1oz/ft^2
 6. Bottom Soldermask
 7. Bottom Silkscreen
3. Finish Thickness should be 0.062"
4. No internal routing
5. All holes shall be plated

Battleship	
PART NO.: UTX-2010F108	REV: A
DATE: 11-04-2010	GERBER: UTX-2010F108
DESIGNER: Stephen Hall Razik Ahmed	Checked by: TA: Harshad

REV 2010

Battleship
P/N: UTX-2010F108 REV A
DESIGNED AT THE UNIVERSITY OF TEXAS AT AUSTIN